



## Description

### JMT P-channel Enhancement Mode Power MOSFET

#### Features

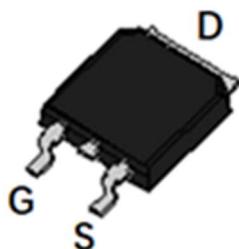
- $V_{DS} = -40V$ ,  $I_D = -15A$
- $R_{DS(ON)} < 35m\Omega$  @  $V_{GS} = -10V$
- $R_{DS(ON)} < 56m\Omega$  @  $V_{GS} = -4.5V$
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead free product is acquired

#### Application

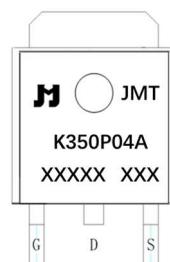
- PWM Applications
- Load Switch
- Power Management



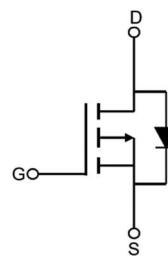
100% UIS TESTED!  
100%  $\Delta V_{ds}$  TESTED!



TO-252(DPAK) top view



Marking and pin Assignment



Schematic Diagram

## Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
JMTK350P04A	JMTK350P04A	TAPING	TO-252	13inch	2500	25000

## Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		-40	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current	$T_c = 25^\circ C$	-15	A
		$T_c = 100^\circ C$	-10	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>		-60	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>note2</sup>		38	mJ
$P_D$	Power Dissipation	$T_c = 25^\circ C$	15	W
$R_{eJC}$	Thermal Resistance, Junction to Case		10	$^\circ C/W$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +175	°C

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

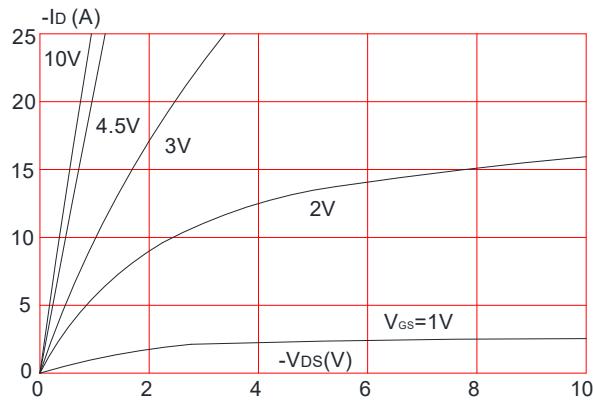
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D = -250\mu\text{A}$	-40	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS} = -40\text{V}$ , $V_{GS}=0\text{V}$	-	-	-1	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS}= \pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D = -250\mu\text{A}$	-1.0	-1.6	-2.5	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS} = -10\text{V}$ , $I_D = -15\text{A}$	-	27	35	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}$ , $I_D = -10\text{A}$	-	40	56	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = -20\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	1273	-	pF
$C_{oss}$	Output Capacitance		-	132	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	98	-	pF
$Q_g$	Total Gate Charge	$V_{DS} = -20\text{V}$ , $I_D = -8\text{A}$ , $V_{GS} = -10\text{V}$	-	24	-	nC
$Q_{gs}$	Gate-Source Charge		-	4.3	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	5.2	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = -20\text{V}$ , $I_D = -15\text{A}$ , $V_{GS} = -10\text{V}$ , $R_{\text{GEN}} = 2.5\Omega$	-	11	-	ns
$t_r$	Turn-on Rise Time		-	16	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	29	-	ns
$t_f$	Turn-off Fall Time		-	15	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current	-	-	-15	-	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	-60	-	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s = -15\text{A}$	-	-0.8	-1.2	V
$trr$	Reverse Recovery Time	$V_{GS} = 0\text{V}$ , $I_s = -15\text{A}$ , $di/dt = 100\text{A}/\mu\text{s}$	-	31	-	ns
$Qrr$	Reverse Recovery Charge		-	23	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

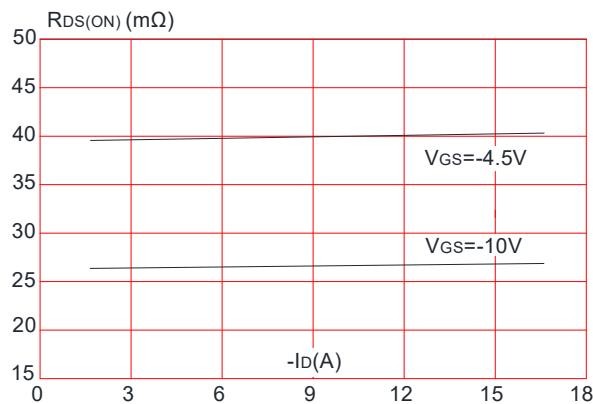
2. EAS condition:  $T_J = 25^\circ\text{C}$ ,  $V_{DD} = -20\text{V}$ ,  $V_G = -10\text{V}$ ,  $L = 0.5\text{mH}$ ,  $R_G = 25\Omega$ ,  $I_{AS} = -12.4\text{A}$ 3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$

## Typical Performance Characteristics

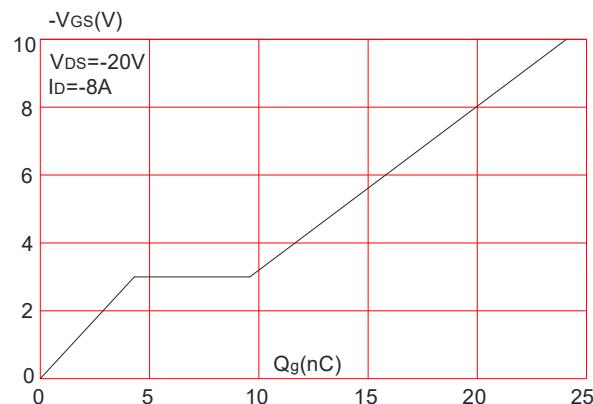
**Figure 1:** Output Characteristics



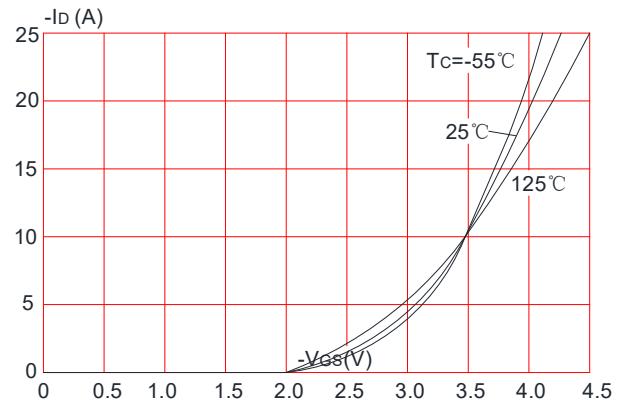
**Figure 3:** On-resistance vs. Drain Current



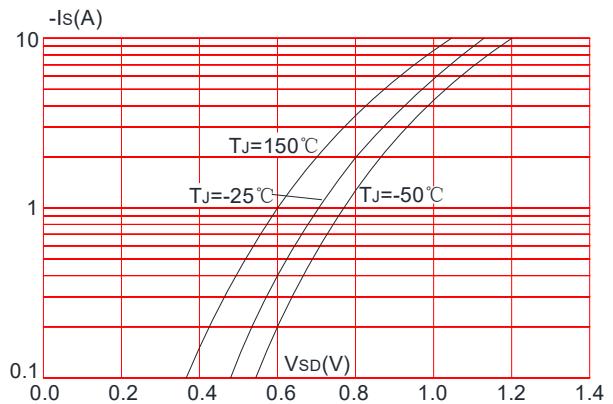
**Figure 5: Gate Charge Characteristics**



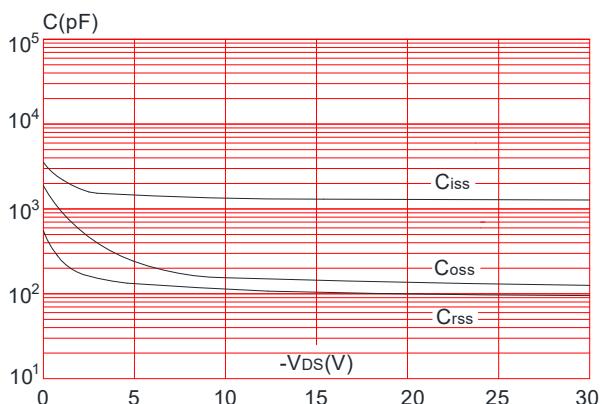
**Figure 2:** Typical Transfer Characteristics



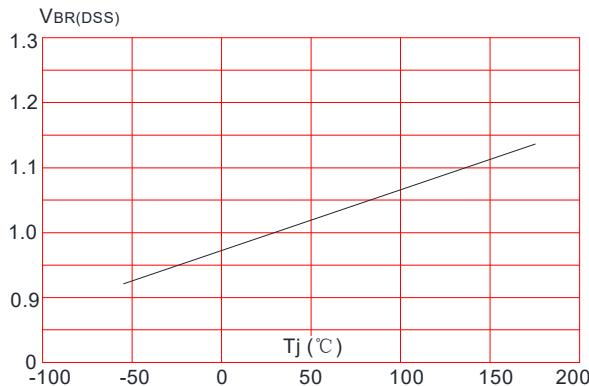
**Figure 4:** Body Diode Characteristics



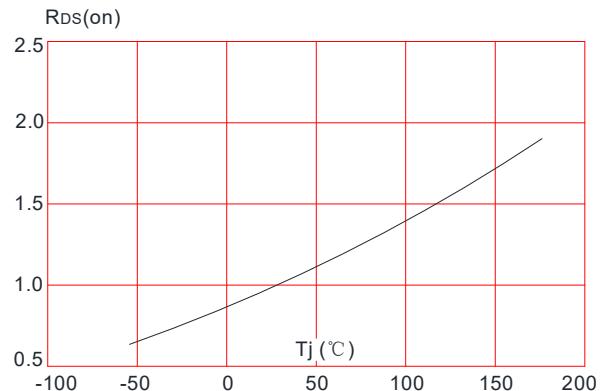
**Figure 6:** Capacitance Characteristics



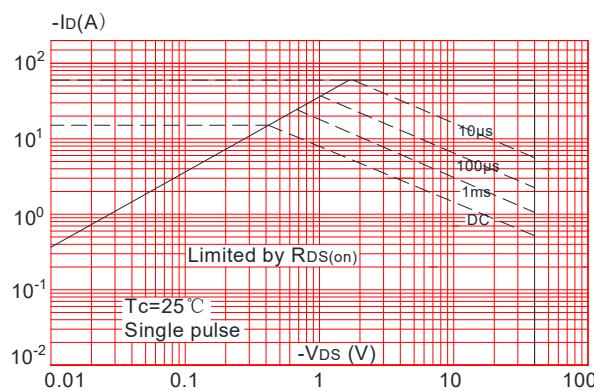
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



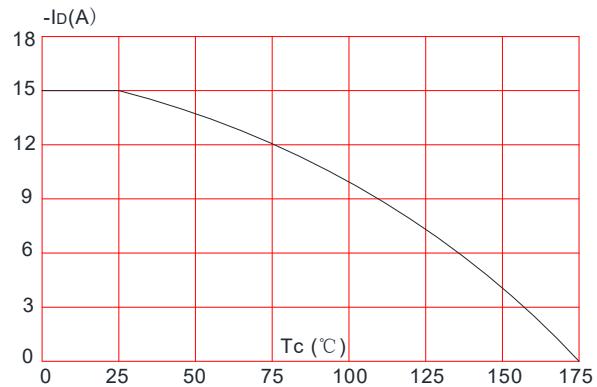
**Figure 8:** Normalized on Resistance vs. Junction Temperature



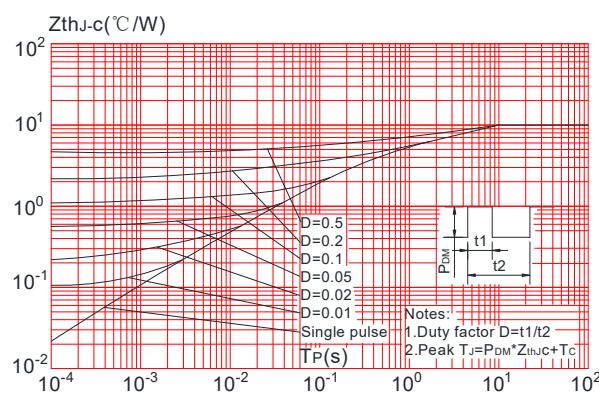
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature

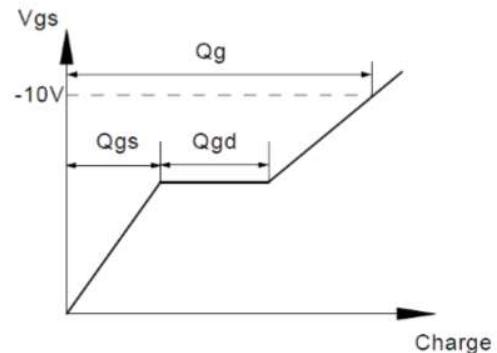
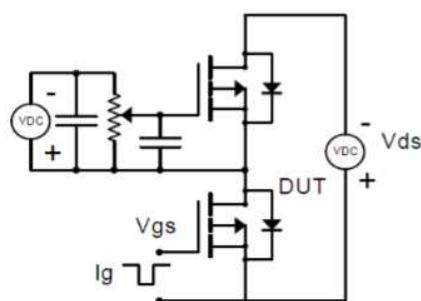


**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case

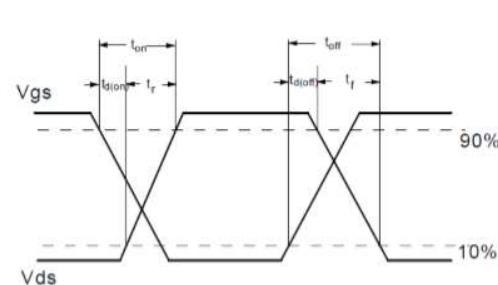
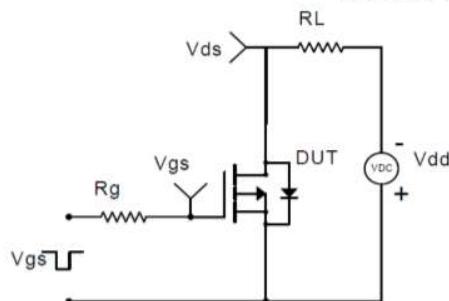


## Test Circuit

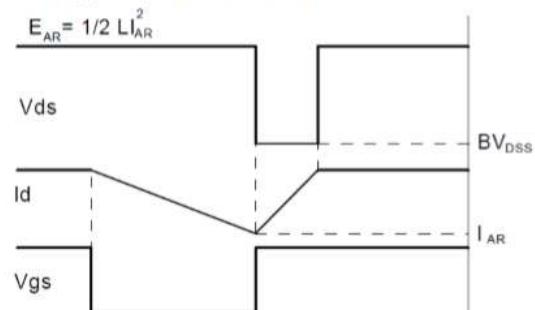
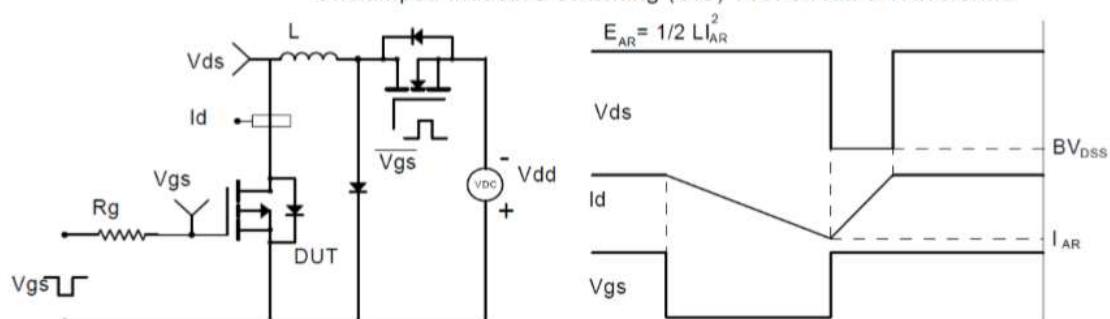
Gate Charge Test Circuit & Waveform



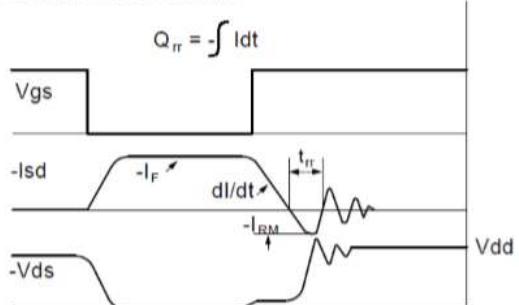
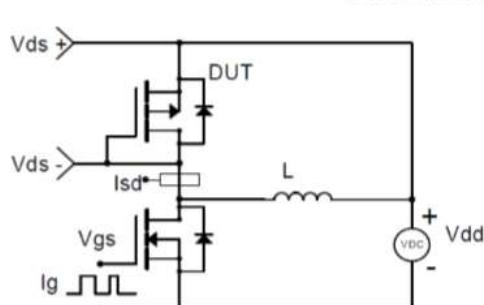
Resistive Switching Test Circuit & Waveforms



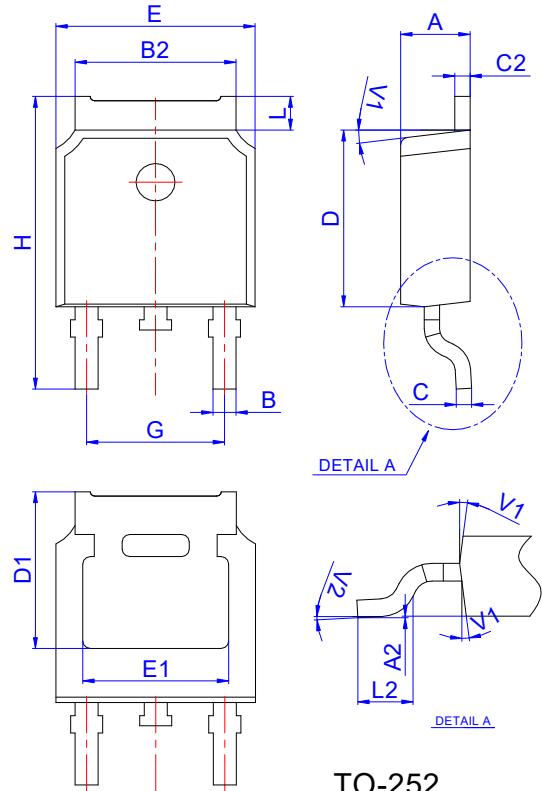
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

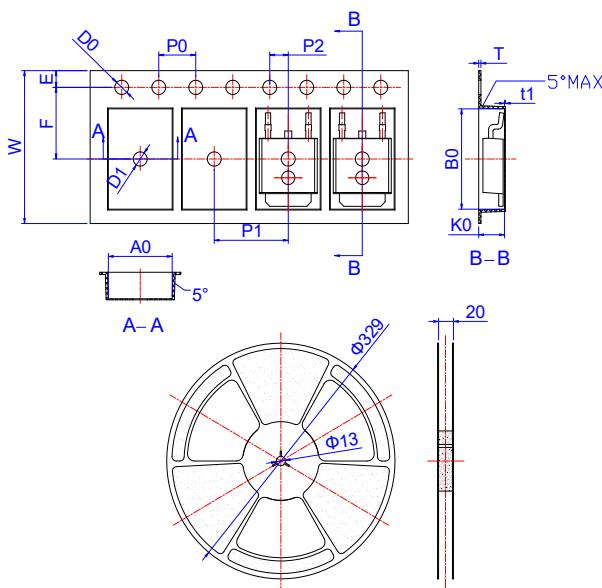


## Package Mechanical Data-TO-252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

## Reel Specification-TO-252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583



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